

Features

- Uses CRM(CQ) advanced Trench technology
- Extremely low on-resistance $R_{DS(on)}$
- Excellent $Q_g \times R_{DS(on)}$ product(FOM)
- Complementary N-ch and P-ch MOSFET

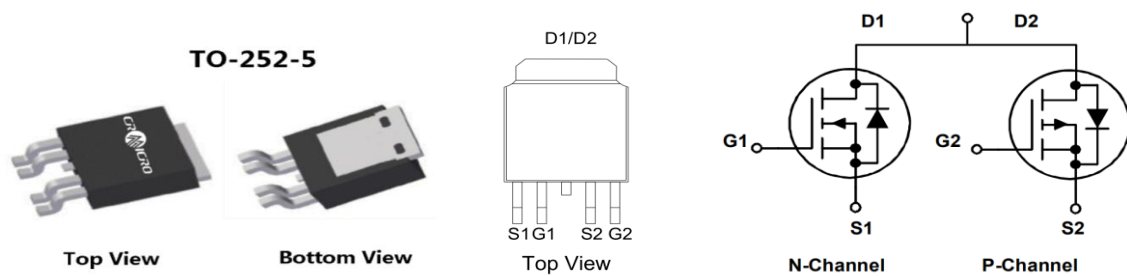
Product Summary

Symbol	N-Ch	P-Ch
V_{DS}	40V	-40V
$R_{DS(on)}$ typ.	9m Ω	27m Ω
I_D	28A	-20A

Applications

- Motor drive

100% DVDS Tested
100% Avalanche Tested



Package Marking and Ordering Information

Part #	Marking	Package	Packing	Reel Size	Tape Width	Qty
CRMV0411C	CRMV0411C	TO-252-5	Taping	N/A	N/A	2500pcs

Absolute Maximum Ratings

Parameter	Symbol	Maximum		Unit
		N-Ch	P-Ch	
Drain-source voltage	V_{DS}	40	-40	V
Continuous drain current $T_C = 25^\circ\text{C}$ (Silicon limit)	I_D	67	-39	A
Continuous drain current $T_C = 25^\circ\text{C}$ (Package limit)	I_D	28	-20	A
Pulsed drain current ($T_C = 25^\circ\text{C}$, t_p limited by T_{jmax})	$I_{D \text{ pulse}}$	112	-80	A
Avalanche energy, single pulse ($L=0.5\text{mH}$, $R_g=25\Omega$)	E_{AS}	49	81	mJ
Gate-Source voltage	V_{GS}	± 20	± 20	V
Power dissipation ($T_C = 25^\circ\text{C}$)	P_{tot}	40.9	40.9	W
Operating junction and storage temperature	T_j, T_{stg}	-55...+150		$^\circ\text{C}$

Thermal Resistance

Parameter	Symbol	Typ	Max	Unit
Thermal resistance, junction – case.	R_{thJC}	2.2	3.1	°C/W
SMD version, device on PCB ¹	R_{thJA}	97.7	117.3	°C/W
Thermal resistance, junction – ambient(min. footprint)				

NOTE:

1.The value of R_{thJA} is measured with the device mounted on 1in2 FR-4 board with 2oz. Copper, in a still air environment with $T_A = 25^{\circ}\text{C}$. The value in any given application depends on the user's specific board design.

N-Channel Electrical Characteristic (at $T_j = 25^{\circ}\text{C}$, unless otherwise specified)

Parameter	Symbol	Value			Unit	Test Condition
		min.	typ.	max.		

Static Characteristic

Drain-source breakdown voltage	BV_{DSS}	40	-	-	V	$V_{GS}=0V, I_D=250\mu A$
Gate threshold voltage	$V_{GS(th)}$	1	1.4	2	V	$V_{DS}=V_{GS}, I_D=250\mu A$
Zero gate voltage drain current	I_{DSS}	-	0.08	1	μA	$V_{DS}=40V, V_{GS}=0V$ $T_j=25^{\circ}\text{C}$ $T_j=125^{\circ}\text{C}$
Gate-source leakage current	I_{GSS}	-	± 10	± 100	nA	$V_{GS}=\pm 20V, V_{DS}=0V$
Drain-source on-state resistance	$R_{DS(on)}$	-	11.0	14.0	m Ω	$V_{GS}=4.5V, I_D=10A$ $V_{GS}=10V, I_D=10A$
Transconductance	g_{fs}	-	46	-	S	$V_{DS}=10V, I_D=10A$

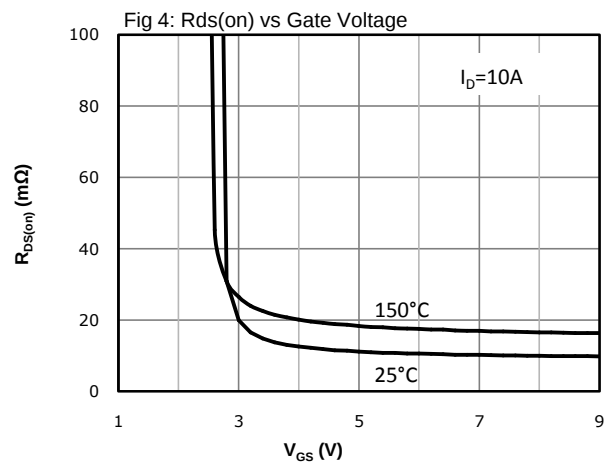
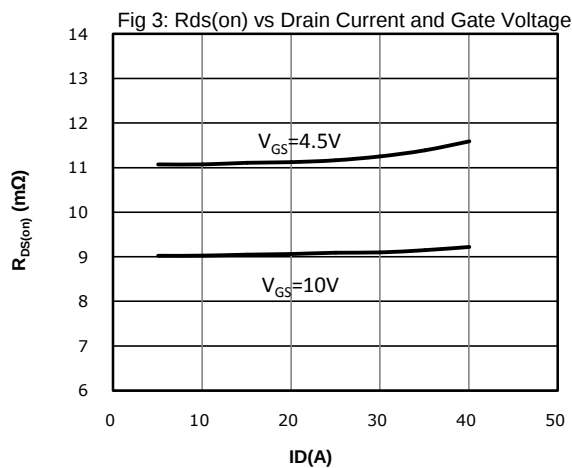
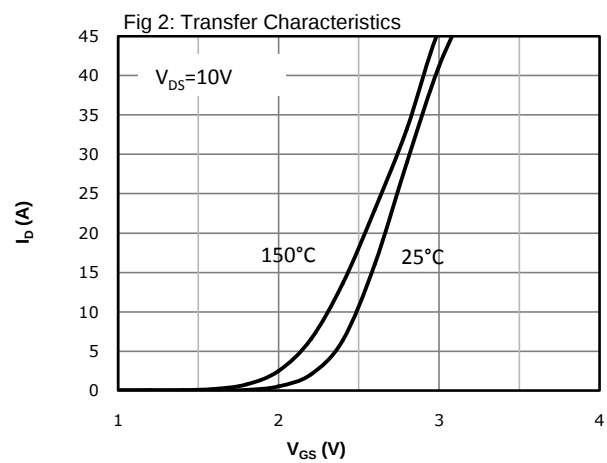
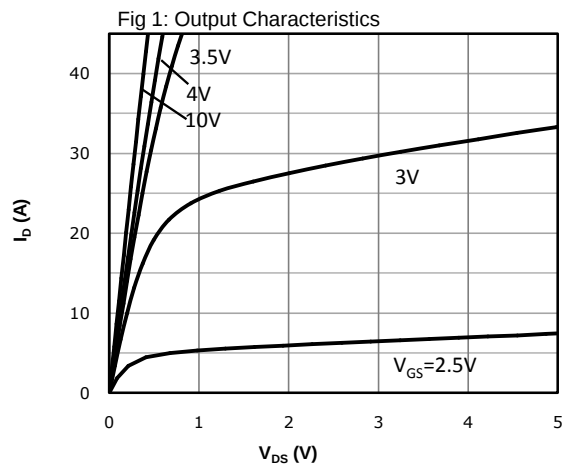
Dynamic Characteristic

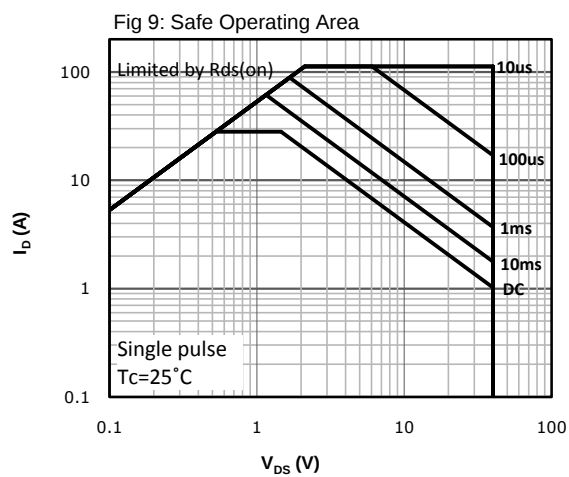
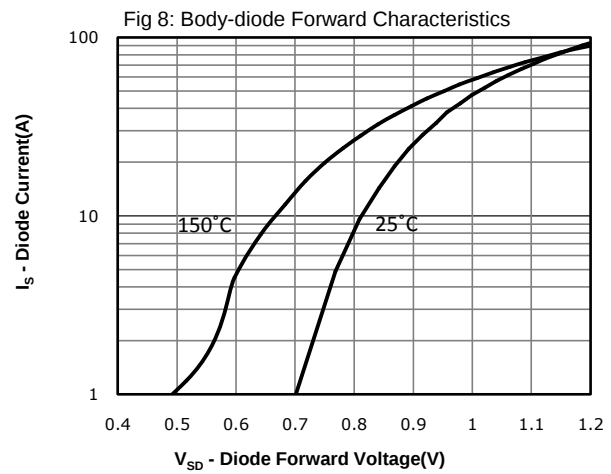
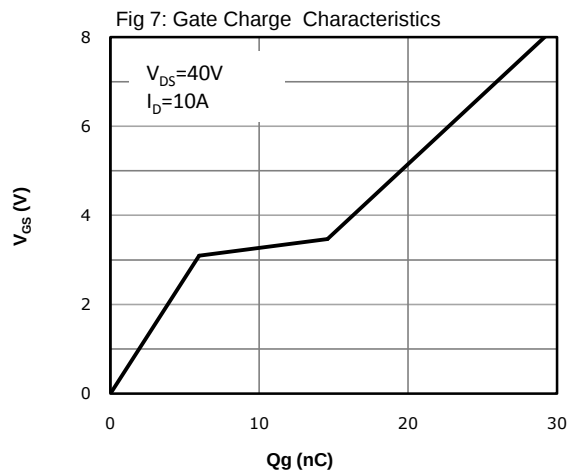
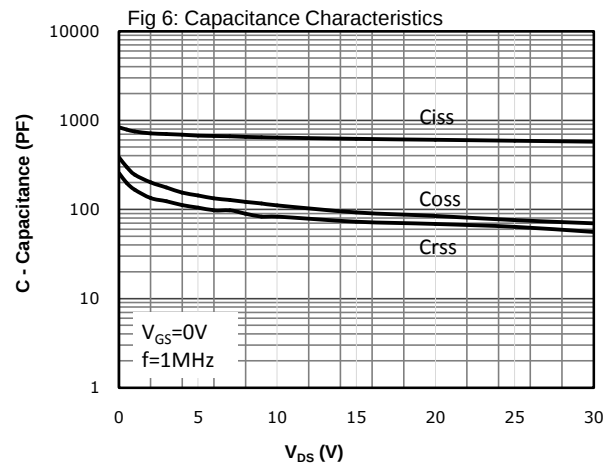
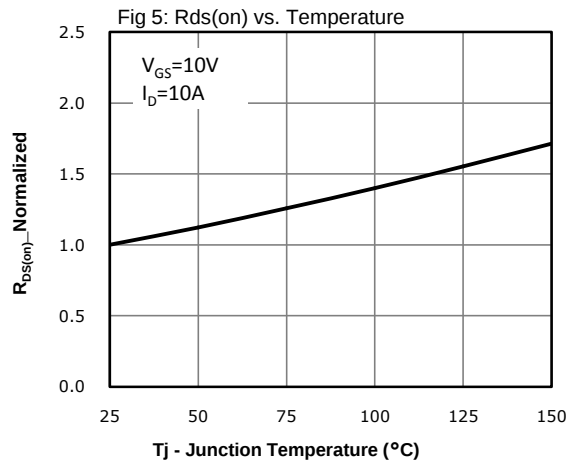
Input Capacitance	C_{iss}	-	1540	-	pF	$V_{GS}=0V, V_{DS}=40V, f=1\text{MHz}$
Output Capacitance	C_{oss}	-	117	-		
Reverse Transfer Capacitance	C_{rss}	-	89	-		
Gate Total Charge	Q_G	-	36	-	nC	$V_{GS}=10V, V_{DS}=40V, I_D=10A, f=1\text{MHz}$
Gate-Source charge	Q_{gs}	-	5.9	-		
Gate-Drain charge	Q_{gd}	-	8.8	-		
Turn-on delay time	$t_{d(on)}$	-	8.9	-	ns	$V_{GS}=10V, V_{DD}=20V, R_{G_ext}=2.7\Omega, I_D=10A$
Rise time	t_r	-	36.2	-		
Turn-off delay time	$t_{d(off)}$	-	28.5	-		
Fall time	t_f	-	45.5	-		
Gate resistance	R_G	-	1.2	-	Ω	$V_{GS}=0V, V_{DS}=0V, f=1\text{MHz}$

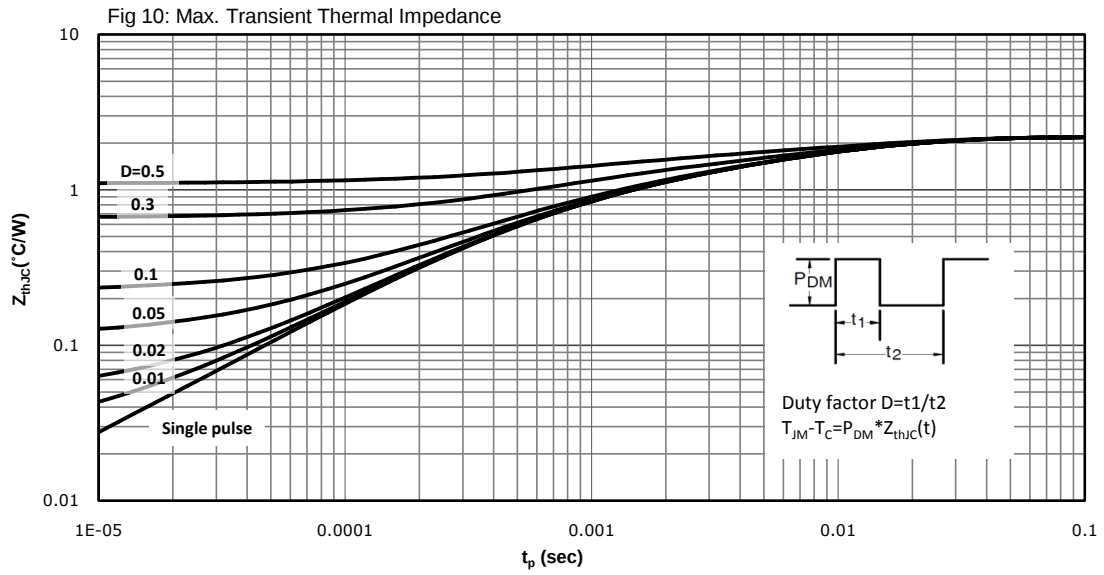
Body Diode Characteristic

Parameter	Symbol	Value			Unit	Test Condition
		min.	typ.	max.		
Body Diode Forward Voltage	V_{SD}	-	0.81	1.20	V	$V_{GS}=0V, I_{SD}=10A$
Body Diode Reverse Recovery Time	t_{rr}	-	13	-	ns	$I_F=10A, dI/dt=100A/\mu s$
Body Diode Reverse Recovery Charge	Q_{rr}	-	4.7	-	nC	

N-Channel Typical Performance Characteristics







P-Channel Electrical Characteristic (at $T_j = 25^\circ\text{C}$, unless otherwise specified)

Parameter	Symbol	Value			Unit	Test Condition
		min.	typ.	max.		

Static Characteristic

Drain-source breakdown voltage	BV_{DSS}	-40	-	-	V	$V_{GS}=0V, I_D=-250\mu A$
Gate threshold voltage	$V_{GS(th)}$	-1.1	-1.8	-2.5	V	$V_{DS}=V_{GS}, I_D=-250\mu A$
Zero gate voltage drain current	I_{DSS}	-	-0.08	-1	μA	$V_{DS}=-40V, V_{GS}=0V$ $T_j=25^\circ\text{C}$ $T_j=125^\circ\text{C}$
Gate-source leakage current	I_{GSS}	-	± 10	± 100	nA	$V_{GS}=\pm 20V, V_{DS}=0V$
Drain-source on-state resistance	$R_{DS(on)}$	-	37.0	45.0	$m\Omega$	$V_{GS}=-4.5V, I_D=-10A$ $V_{GS}=-10V, I_D=-10A$
Transconductance	g_{fs}	-	24.2	-	S	$V_{DS}=-10V, I_D=-10A$

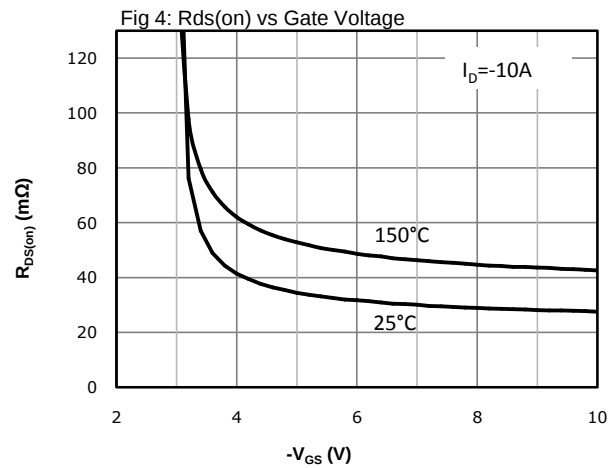
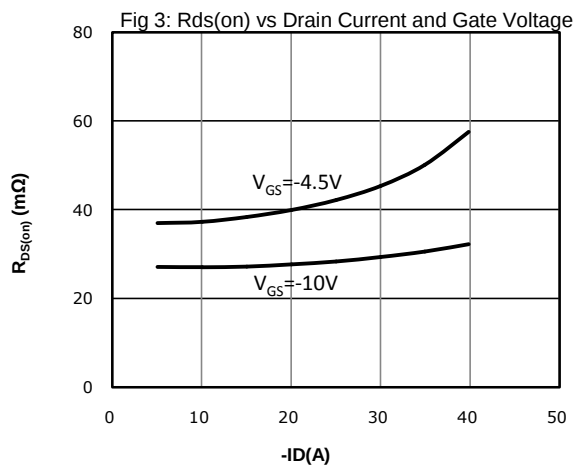
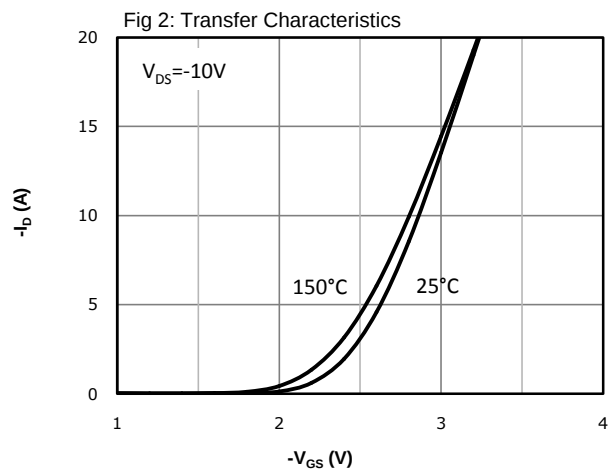
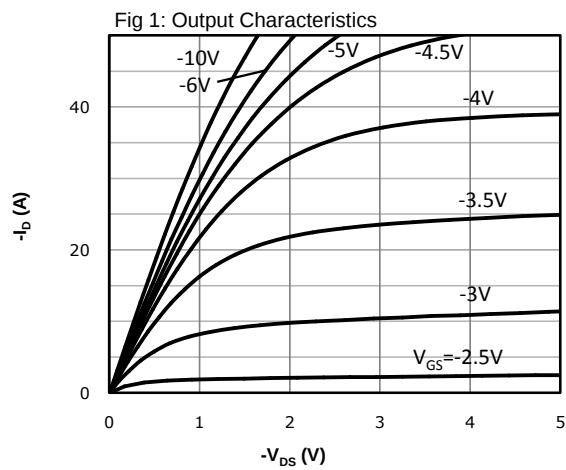
Dynamic Characteristic

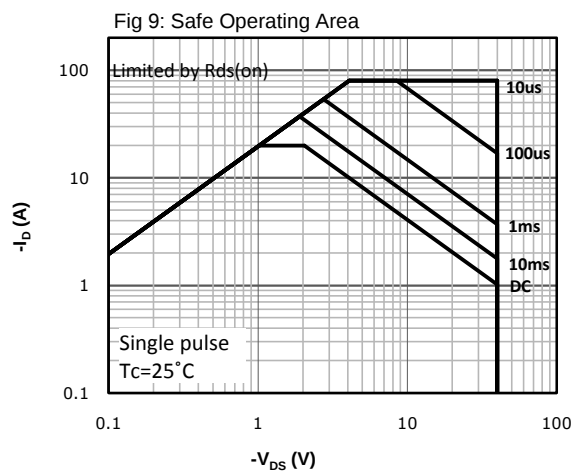
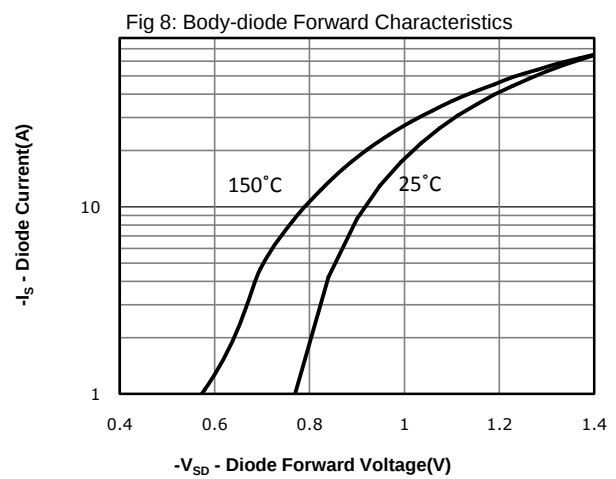
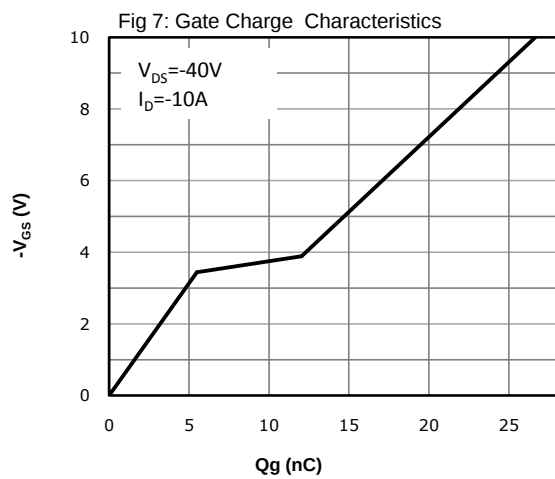
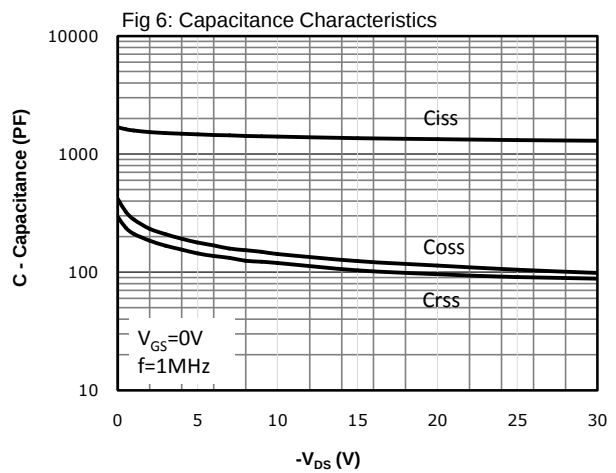
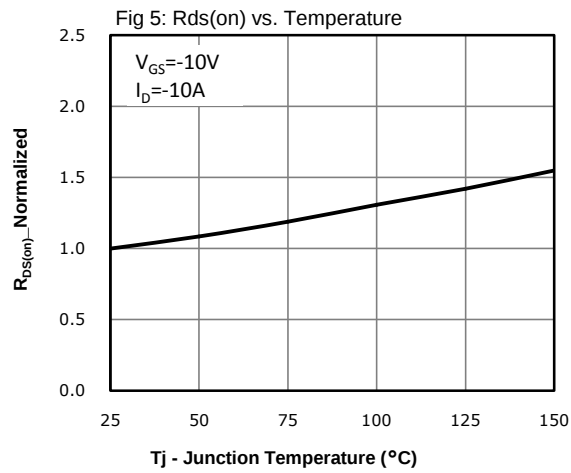
Input Capacitance	C_{iss}	-	1268	-	pF	$V_{GS}=0V, V_{DS}=-40V, f=1\text{MHz}$
Output Capacitance	C_{oss}	-	89	-		
Reverse Transfer Capacitance	C_{rss}	-	80	-		
Gate Total Charge	Q_G	-	27	-	nC	$V_{GS}=-10V, V_{DS}=-40V,$ $I_D=-10A, f=1\text{MHz}$
Gate-Source charge	Q_{gs}	-	5.5	-		
Gate-Drain charge	Q_{gd}	-	6.5	-		
Turn-on delay time	$t_{d(on)}$	-	7.5	-	ns	$V_{GS}=-10V, V_{DD}=-20V,$ $R_{G_ext}=2.7\Omega, I_D=-10A$
Rise time	t_r	-	36.7	-		
Turn-off delay time	$t_{d(off)}$	-	33.5	-		
Fall time	t_f	-	56.9	-		
Gate resistance	R_G	-	8.8	-	Ω	$V_{GS}=0V, V_{DS}=0V, f=1\text{MHz}$

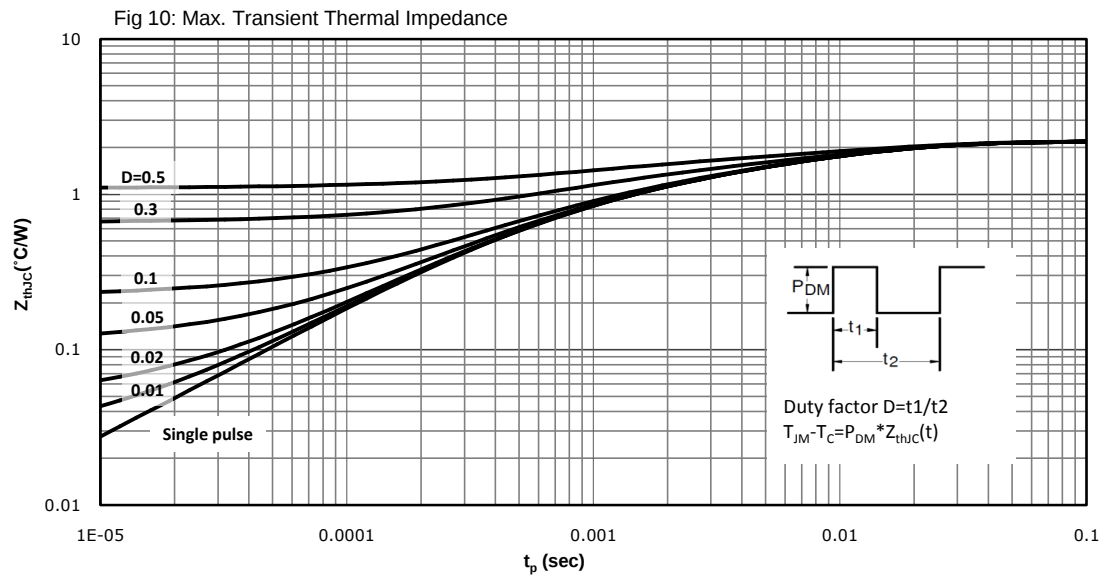
Body Diode Characteristic

Parameter	Symbol	Value			Unit	Test Condition
		min.	typ.	max.		
Body Diode Forward Voltage	V_{SD}	-	-0.92	-1.20	V	$V_{GS}=0V, I_{SD}=-10A$
Body Diode Reverse Recovery Time	t_{rr}	-	14.6	-	ns	$I_F=10A, dI/dt=100A/\mu s$
Body Diode Reverse Recovery Charge	Q_{rr}	-	7.8	-	nC	

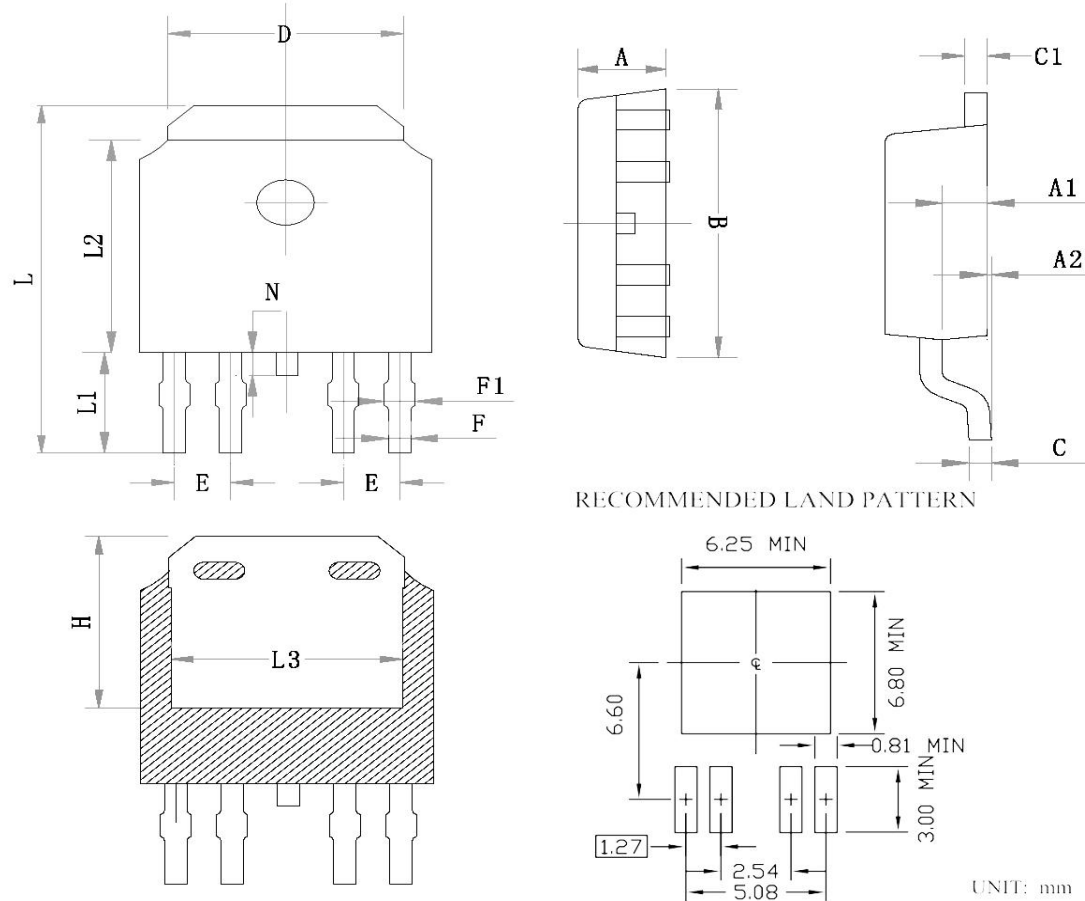
P-Channel Typical Performance Characteristics







Package Outline: TO-252-5



SYMBOLS	DIMENSIONS IN MILLIMETERS			DIMENSIONS IN INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	2.20	2.30	2.40	0.087	0.091	0.094
A1	0.91	1.01	1.11	0.036	0.040	0.044
A2	0.00	----	0.25	0.000	----	0.010
B	6.40	6.60	6.80	0.252	0.260	0.268
C	0.45	0.50	0.58	0.018	0.020	0.023
C1	0.45	0.50	0.58	0.018	0.020	0.023
D	5.12	5.32	5.52	0.202	0.209	0.217
E	1.27 BSC			0.050 BSC		
F	0.40	0.50	0.60	0.016	0.020	0.024
F1	0.45	0.65	0.80	0.018	0.026	0.031
H	4.57	4.85	5.10	0.180	0.191	0.201
L	9.40	9.90	10.20	0.370	0.390	0.402
L1	2.40	2.75	3.00	0.094	0.108	0.118
L2	5.40	5.80	6.25	0.213	0.228	0.246
L3	5.00	5.30	5.50	0.197	0.209	0.217
N	0.45	----	1.20	0.018	----	0.047

NOTE

- 1.PACKAGE BODY SIZES EXCLUDE MOLD FLASH AND GATE BURRS.
MOLD FLASH SHOULD BE LESS THAN 6MIL
- 2.DIMENSION L IS MEASURED IN GAUGE PLANE.
- 3.TOLERANCE 0.10mm UNLESS OTHER WISE SPECIFIED.
- 4.CONTROLLING DIMENSION IS MILLIMETER.
CONVERTED INCH DIMENSIONS ARE NOT NECESSARILY EXACT.

Revision History

Revision	Date	Major changes
1.1	2022/12/15	Release of formal version

Disclaimer

Unless otherwise specified in the datasheet, the product is designed and qualified as a standard commercial product and is not intended for use in applications that require extraordinary levels of quality and reliability, such as automotive, aviation/aerospace and life-support devices or systems.

Any and all semiconductor products have certain probability to fail or malfunction, which may result in personal injury, death or property damage. Customer are solely responsible for providing adequate safe measures when design their systems.

This product is suitable for reflow soldering up to 260°C, not very suitable for wave soldering.

The reliability of this product is not guaranteed under specific conditions when accepted by customers.

CRM(CQ) reserves the right to improve product design, function and reliability without notice.